

APPLICATION DATA SHEET (37 C.F.R. 1.76)

INVENTOR & RESIDENCE: Martin Alter, Los Altos, California
Robert Rumsey, Saratoga, California

CORRESPONDENCE ADDRESS: Eugene H. Valet
ValetPatents
314 10th Ave. South
Edmonds WA 98020
425-672-3147 1 fax 640-0525

TITLE: Integrating Chip Scale Packaging Metallization Into
Integrated Circuit Die Structures

DRAWING SHEETS: 4
SUGGESTED PUBL. FIG. NO.: 3A
DOCKET NO.: M-077P1
TYPE: UTILITY
ATTORNEY, REG. NO.: J. Vincent Tortolano, Reg. No. 31,433
Eugene H. Valet, 31,435

PRIORITY INFORMATION: Continuation-In-Part of Ser. No. 10/453,157
ASSIGNEE: Micrel, Incorporated, San Jose, California